

NCE0102Z-VB Datasheet N-Channel 100 V (D-S) MOSFET

MOSFET PRODUCT SUMMARY					
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^a	Q _g (Typ.)		
	0.240 at V _{GS} = 10 V	2.0			
100	0.250 at V _{GS} = 6 V	1.8	2.9 nC		
	0.260 at V _{GS} = 4.5 V	1.7			

FEATURES

- Trench Power MOSFET
- 100 % R_g Tested
 100 % UIS Tested
- Material categorization:



DC/DC Converters

Load Switch

APPLICATIONS

• LED Backlighting in LCD TVs

Parameter Drain-Source Voltage Gate-Source Voltage		Symbol	Limit	Unit
		V _{DS}	100	V
		V _{GS}	± 20	v
Continuous Drain Current (T _J = 150 °C)	$T_{C} = 25 \text{ °C}$ $T_{C} = 70 \text{ °C}$ $T_{A} = 25 \text{ °C}$ $T_{A} = 70 \text{ °C}$	I _D	2 1.8 1.6 ^{b, c} 1.3 ^{b, c}	
Pulsed Drain Current (t = 300 µs)		I _{DM}	7	— A
Continuous Source-Drain Diode Current	T _C = 25 °C T _A = 25 °C	I _S	2.1 1.0 ^{b, c}	
Single Pulse Avalanche Current	1 0.1 ml l	I _{AS}	5	
Single Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	1.25	mJ
Maximum Power Dissipation	$T_{C} = 25 \text{ °C}$ $T_{C} = 70 \text{ °C}$ $T_{A} = 25 \text{ °C}$ $T_{A} = 70 \text{ °C}$	P _D	2.5 1.6 1.25 ^{b, c} 0.8 ^{b, c}	w
Operating Junction and Storage Temperature Range		T _J , T _{stq}	- 55 to 150	°C

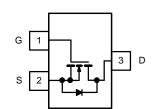
TINGS				
	Symbol	Typical	Maximum	Unit
≤ 5 s	R _{thJA}	75	100	°C/W
Steady State	R _{thJF}	40	50	0/00
		Symbol ≤ 5 s R _{thJA}	Symbol Typical ≤ 5 s R _{thJA} 75	SymbolTypicalMaximum ≤ 5 s R_{thJA} 75100

Notes: a. Based on T_C = 25 °C.

b. Surface mounted on 1" x 1" FR4 board.

c. t = 5 s.

d. Maximum under steady state conditions is 166 °C/W.





Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static						1	
Drain-Source Breakdown Voltage	V _{DS}	$V_{DS} = 0 V, I_{D} = 250 \mu A$	100			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$			105		mV/°0	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 5.2			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	1.2		2.8	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 100 V, V _{GS} = 0 V			- 1	μA	
Zero Gate Voltage Drain Current		V_{DS} = 100 V, V_{GS} = 0 V, T_{J} = 55 °C			- 10		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \geq 5$ V, V_{GS} = 4.5 V	5			Α	
		V _{GS} = 10 V, I _D = 1.5 A		0.240			
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 6 V, I _D = 1 A		0.250		Ω	
		V _{GS} = 4.5 V, I _D = 0.5 A		0.260		1	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 20 V, I _D = 1.5 A		2.0		S	
Dynamic ^b					I	1	
Input Capacitance	C _{iss}			190			
Output Capacitance	C _{oss}	V _{DS} = 50 V, V _{GS} = 0 V, f = 1 MHz		22		pF	
Reverse Transfer Capacitance	C _{rss}			13			
		$V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 1.6 \text{ A}$		5.2	10.4		
Total Gate Charge	Qg			2.9	5.8	nC	
Gate-Source Charge	Q _{gs}	$V_{DS} = 50$ V, $V_{GS} = 4.5$ V, $I_{D} = 1.6$ A		0.75			
Gate-Drain Charge	Q _{gd}			1.4			
Gate Resistance	R _g	f = 1 MHz	0.3	1.4	2.8	Ω	
Turn-On Delay Time	t _{d(on)}			30	45		
Rise Time	t _r	V_{DD} = 50 V, R_{L} = 39 Ω		26	39	-	
Turn-Off Delay Time	t _{d(off)}	$I_{D} = 1.3 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_{g} = 1 \Omega$		17	26		
Fall Time	t _f			12	20		
Turn-On Delay Time	t _{d(on)}			6	12	ns	
Rise Time	t _r	$V_{DD} = 50 \text{ V}, \text{ R}_{L} = 39 \Omega$		10	20	-	
Turn-Off Delay Time	t _{d(off)}	$I_{\rm D}$ = 1.3 Å, $V_{\rm GEN}$ = 10 V, $R_{\rm g}$ = 1 Ω		10	20		
Fall Time	t _f			6	12		
Drain-Source Body Diode Characteristi	cs				I	1	
Continuous Source-Drain Diode Current	۱ _S	T _C = 25 °C			- 2.1	Γ.	
Pulse Diode Forward Current ^a	I _{SM}				- 20	A	
Body Diode Voltage	V _{SD}	I _S = 1.3 A		- 0.8	- 1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			22	33	ns	
Body Diode Reverse Recovery Charge	Q _{rr}			21	32	nC	
Reverse Recovery Fall Time	t _a	I _F = 1.3 A, dl/dt = 100 A/μs, T _J = 25 °C		16		1	
Reverse Recovery Rise Time	t _b			6		ns	

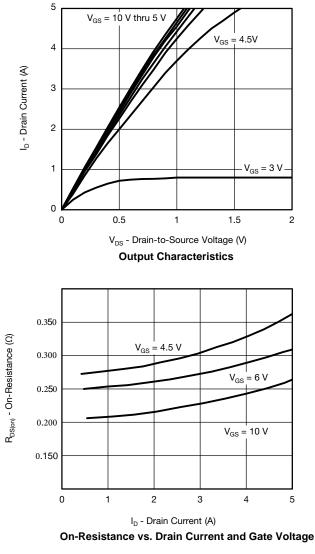
Notes:

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

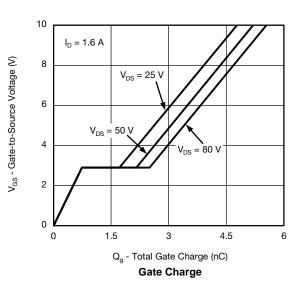
b. Guaranteed by design, not subject to production testing.

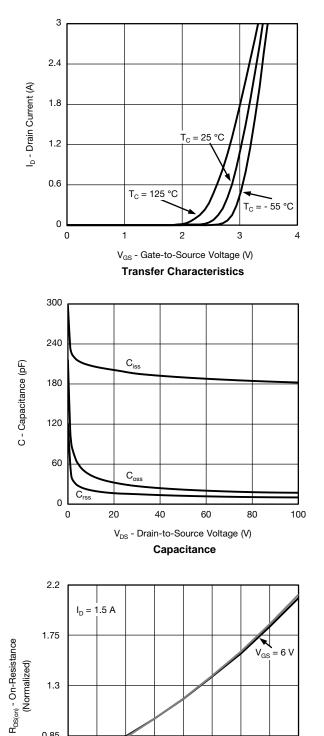
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

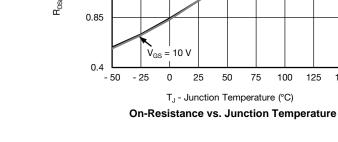




TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





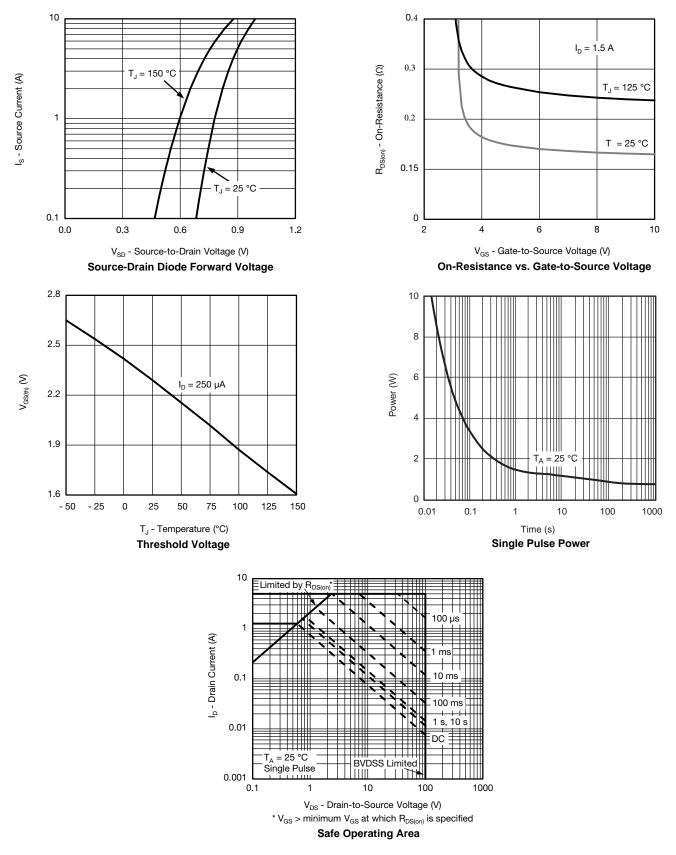


150

100

125

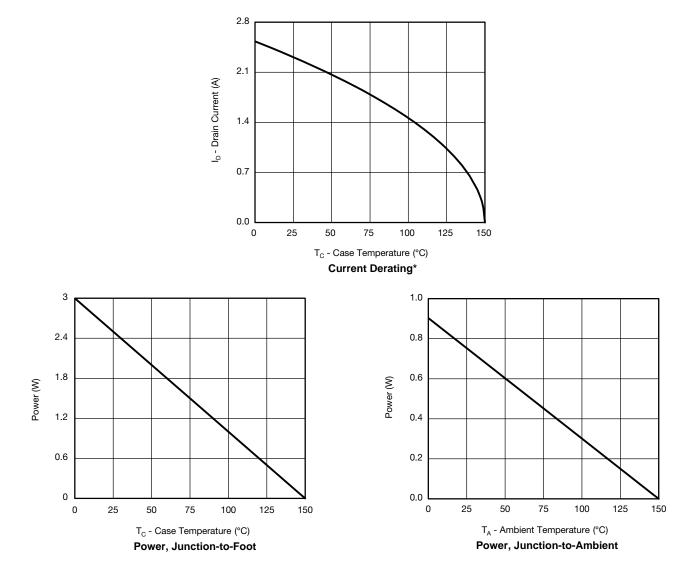




TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



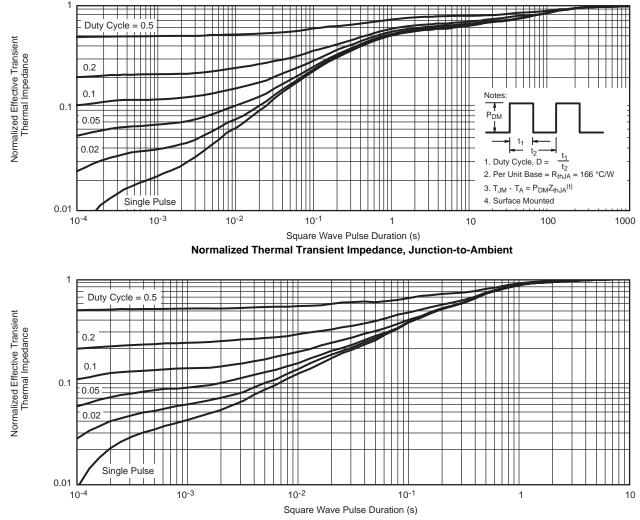
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



* The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Foot

Note

The characteristics shown in the two graphs

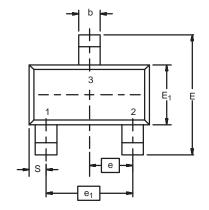
- Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)

- Normalized Transient Thermal Impedance Junction-to-Foot (25 C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.



SOT-23 (TO-236): 3-LEAD







Dim —	MILLIN	IETERS	INCHES		
	Min	Max	Min	Мах	
Α	0.89	1.12	0.035	0.044	
A ₁	0.01	0.10	0.0004	0.004	
A ₂	0.88	1.02	0.0346	0.040	
b	0.35	0.50	0.014	0.020	
C	0.085	0.18	0.003	0.007	
D	2.80	3.04	0.110	0.120	
E	2.10	2.64	0.083	0.104	
E ₁	1.20	1.40	0.047	0.055	
е	0.95 BSC		0.0374 Ref		
e ₁	1.90 BSC		0.0748 Ref		
L	0.40	0.60	0.016	0.024	
L ₁	0.64 Ref		0.025 Ref		
S	0.50 Ref		0.020 Ref		
q	3°	8°	3°	8°	



RECOMMENDED MINIMUM PADS FOR SOT-23



Recommended Minimum Pads Dimensions in Inches/(mm)



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